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(12) **United States Design Patent**
Wang

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(54) **THERMAL INFRARED IMAGER**
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(**) Term: **14 Years**
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(51) **LOC (9) Cl.** **16-06**
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(58) **Field of Classification Search** D16/130,
D16/132, 133, 206, 200, 201, 203; 359/630;
D10/46, 66, 50, 70; 33/290, 291, 292, 285
See application file for complete search history.

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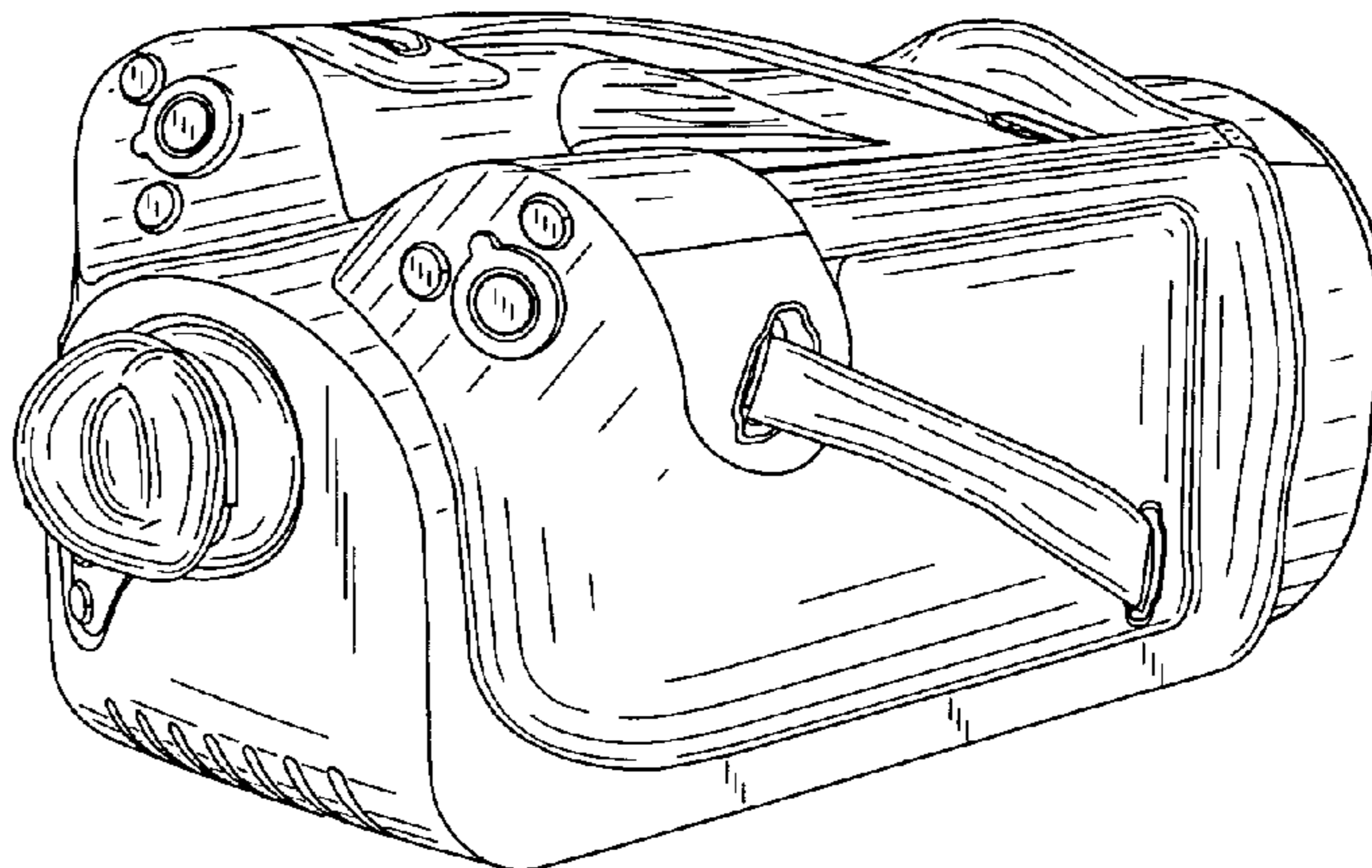
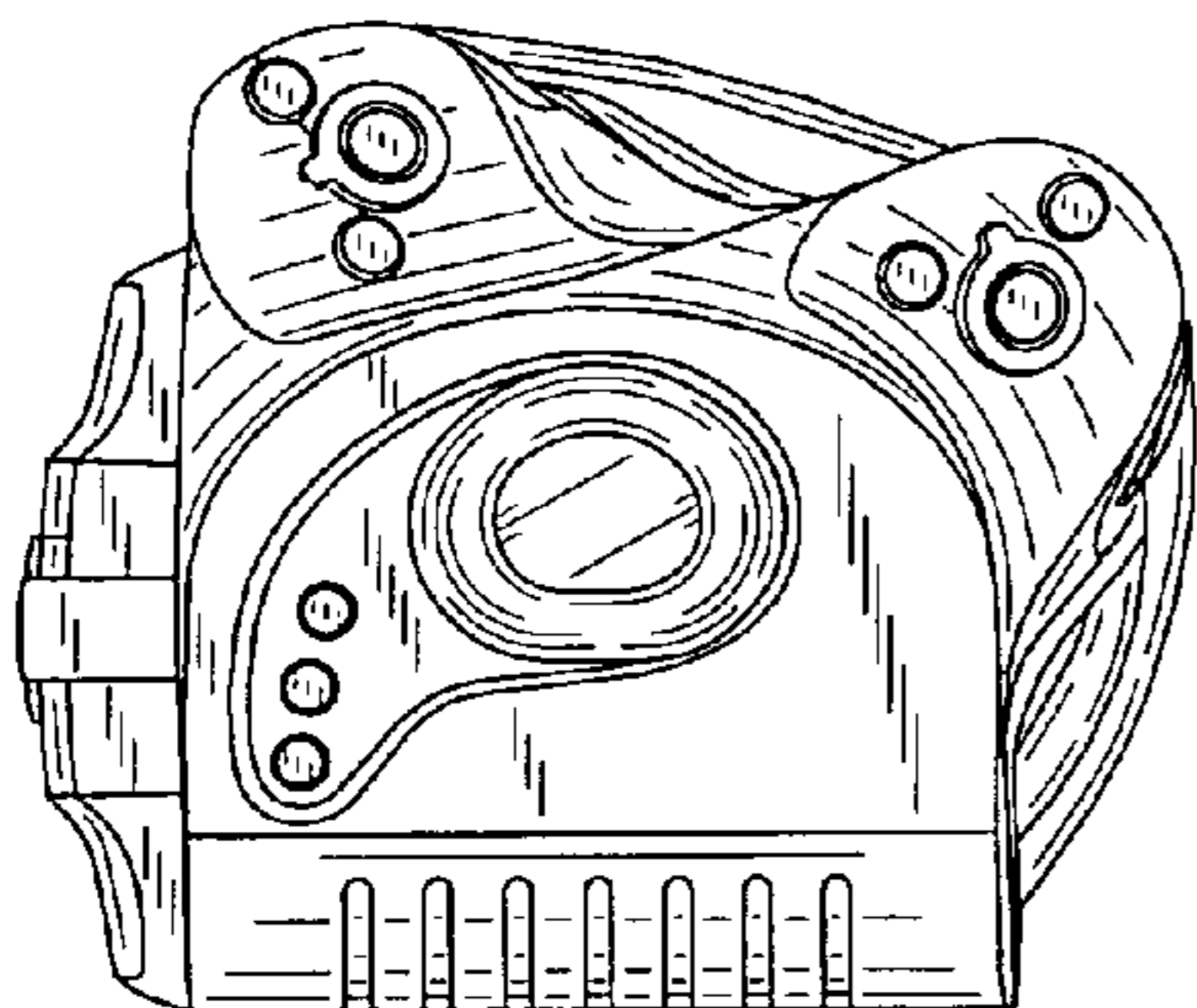
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Jiwen Chen

(57) **CLAIM**
I claim the ornamental design for the thermal infrared imager, as shown and described.

DESCRIPTION

FIG. 1 is a front elevational view of the thermal infrared imager when it is in a closed position;
FIG. 2 is a rear elevational view of the thermal infrared imager when it is in a closed position;
FIG. 3 is a bottom plan view of the thermal infrared imager when it is in a closed position;
FIG. 4 is a top plan view of the thermal infrared imager when it is in a closed position;
FIG. 5 is a left side view of the thermal infrared imager when it is in a closed position;
FIG. 6 is a right side view of the thermal infrared imager when it is in a closed position;
FIG. 7 is a rear perspective view of the thermal infrared imager when it is in a closed position;
FIG. 8 is a right side view of the thermal infrared imager when it is in an open position;
FIG. 9 is a front elevational view of the thermal infrared imager when it is in an open position;
FIG. 10 is a rear elevational view of the thermal infrared imager when it is in an open position;
FIG. 11 is a top plan view of the thermal infrared imager when it is in an open position; and,
FIG. 12 is a bottom plan view of the thermal infrared imager when it is in an open position.
The broken lines form no part of the claimed design.

1 Claim, 6 Drawing Sheets



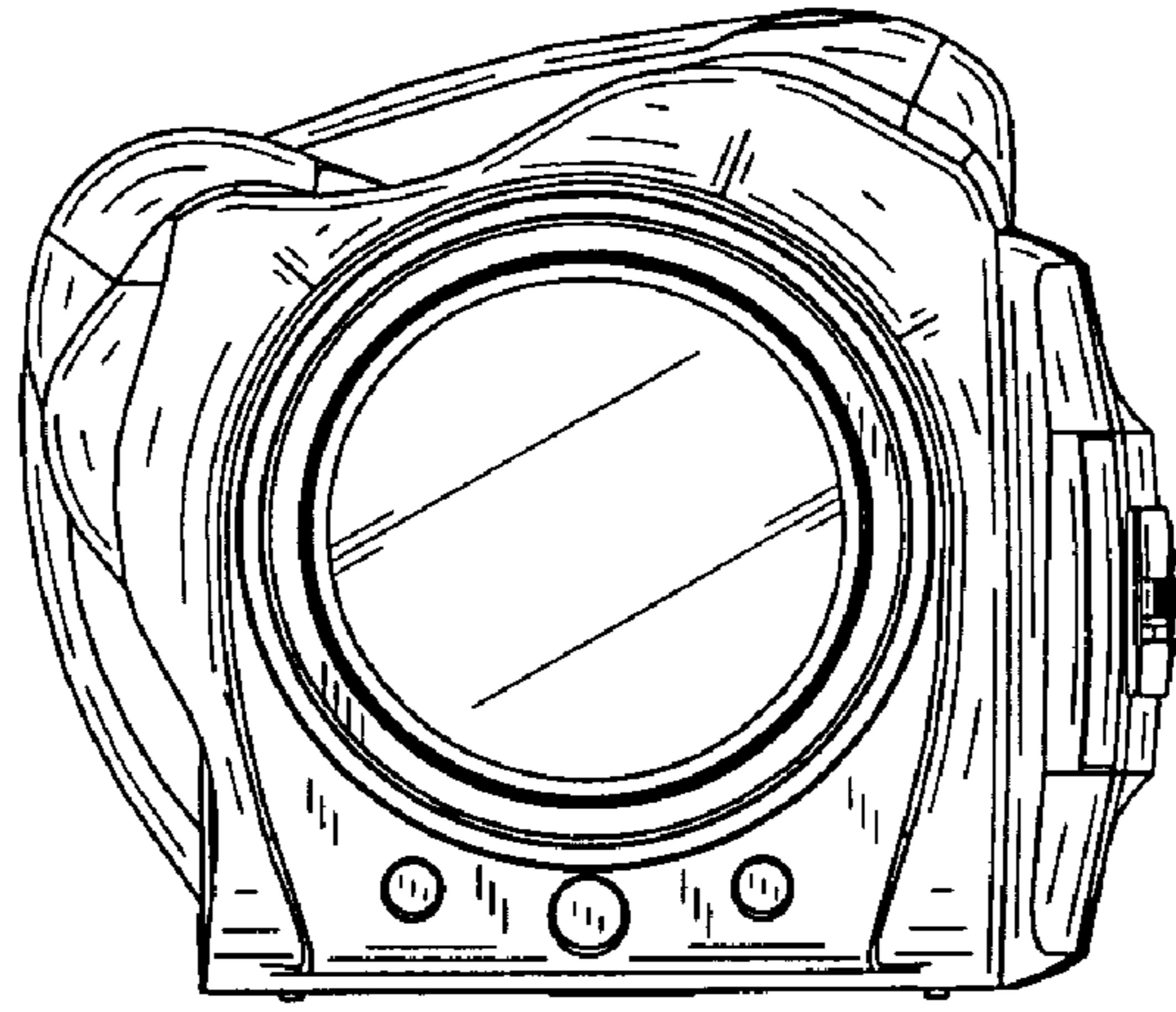


Fig. 1

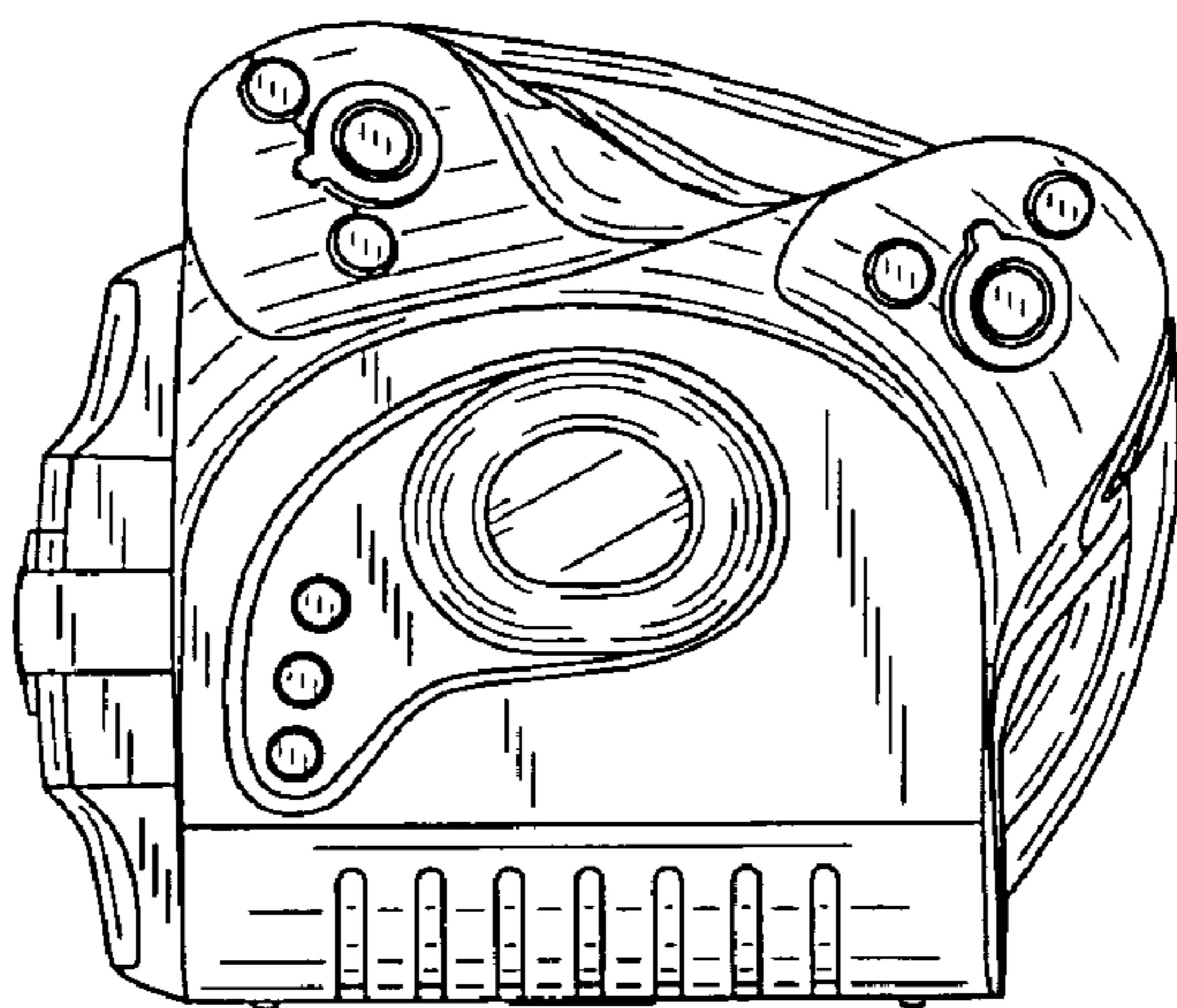


Fig. 2

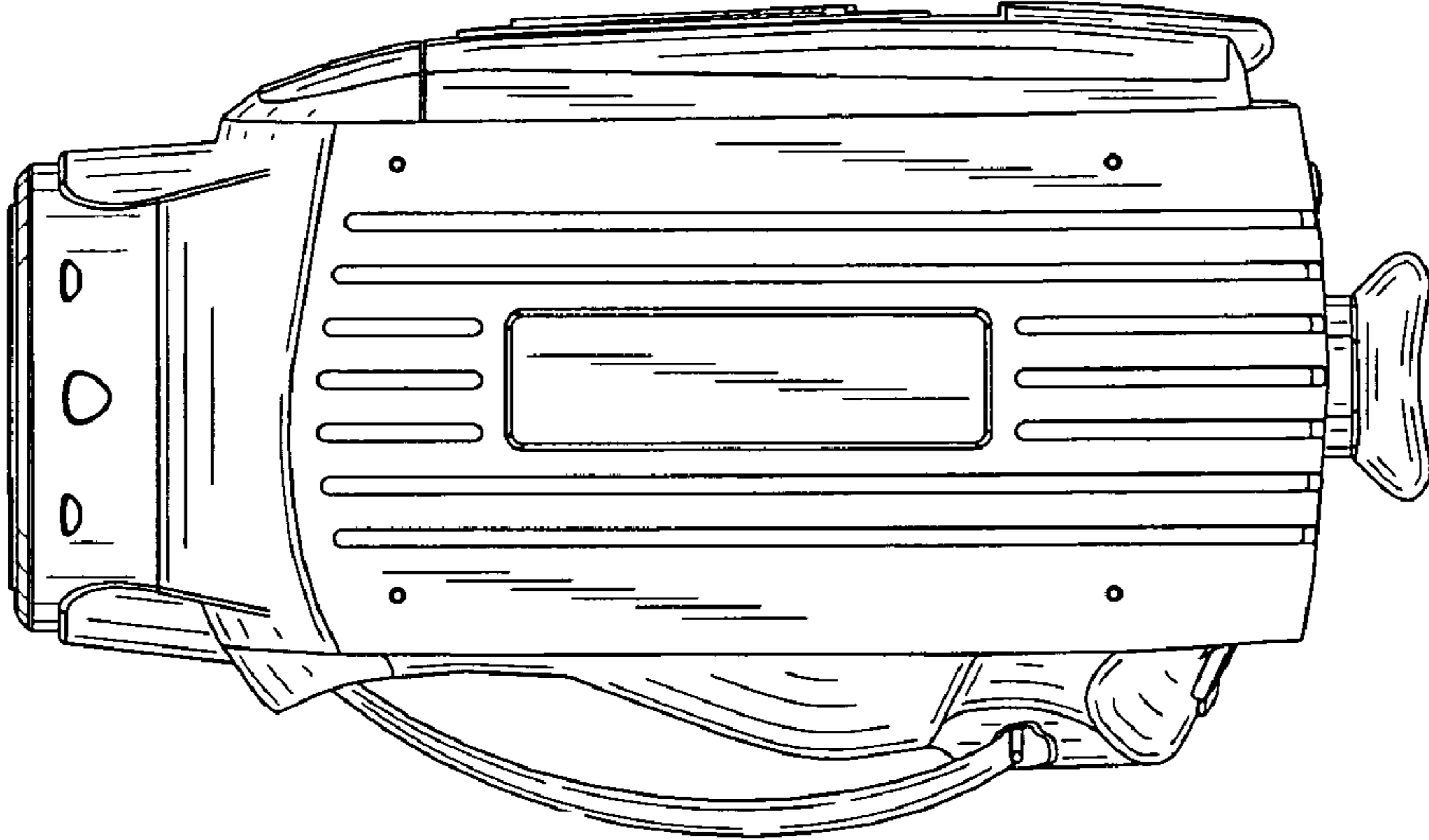


Fig. 3

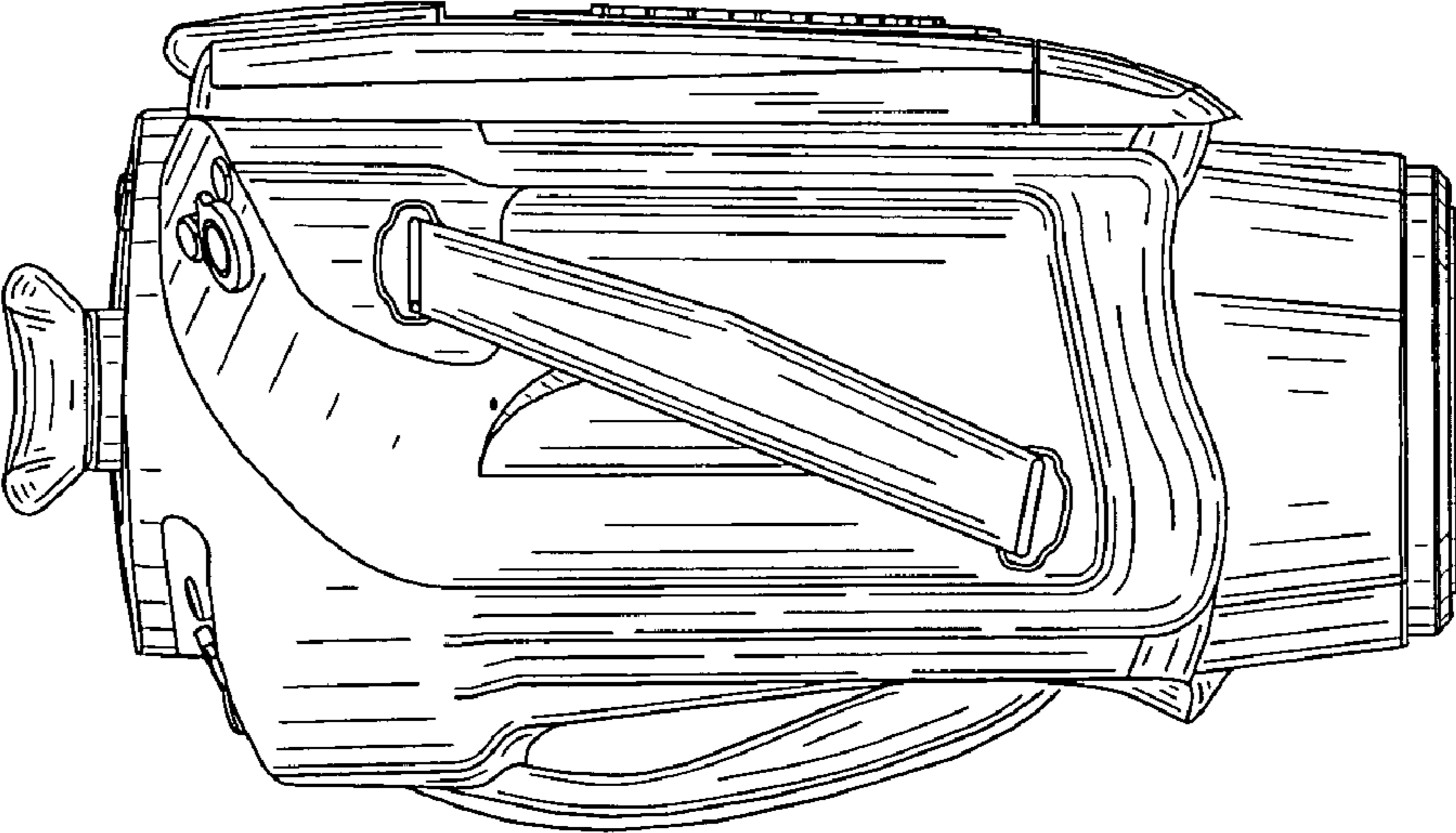


Fig. 4

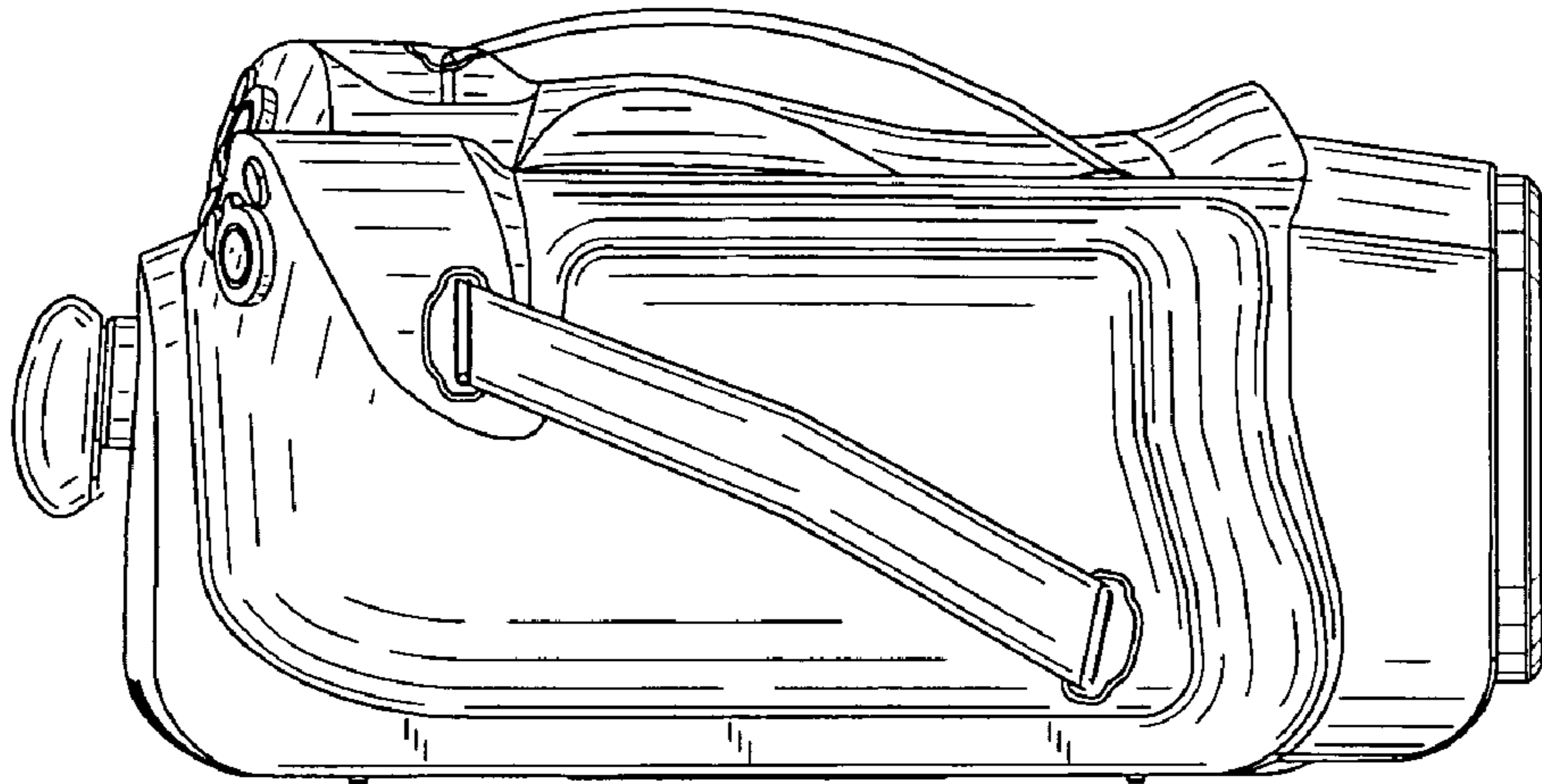


Fig. 5

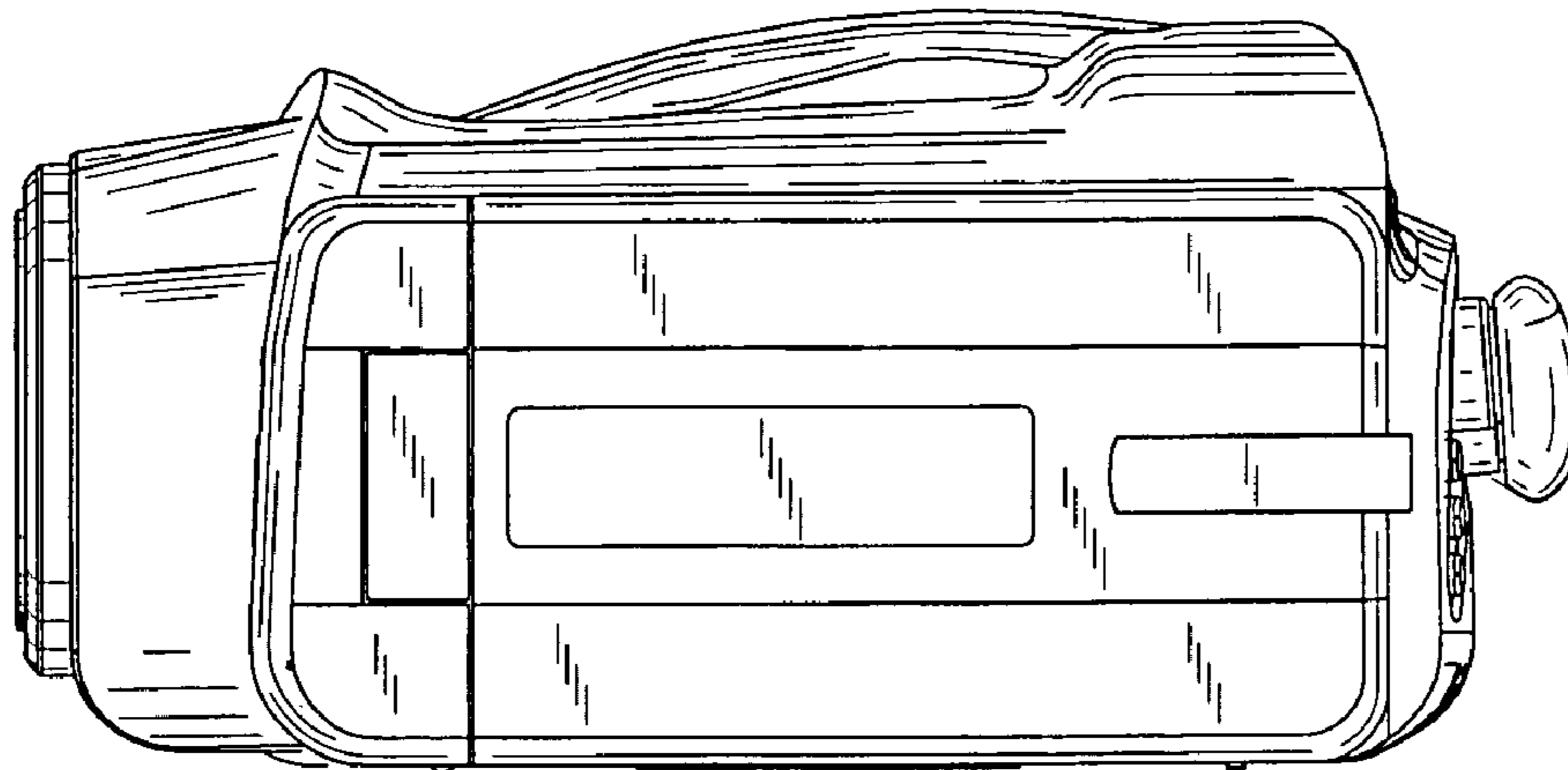


Fig. 6

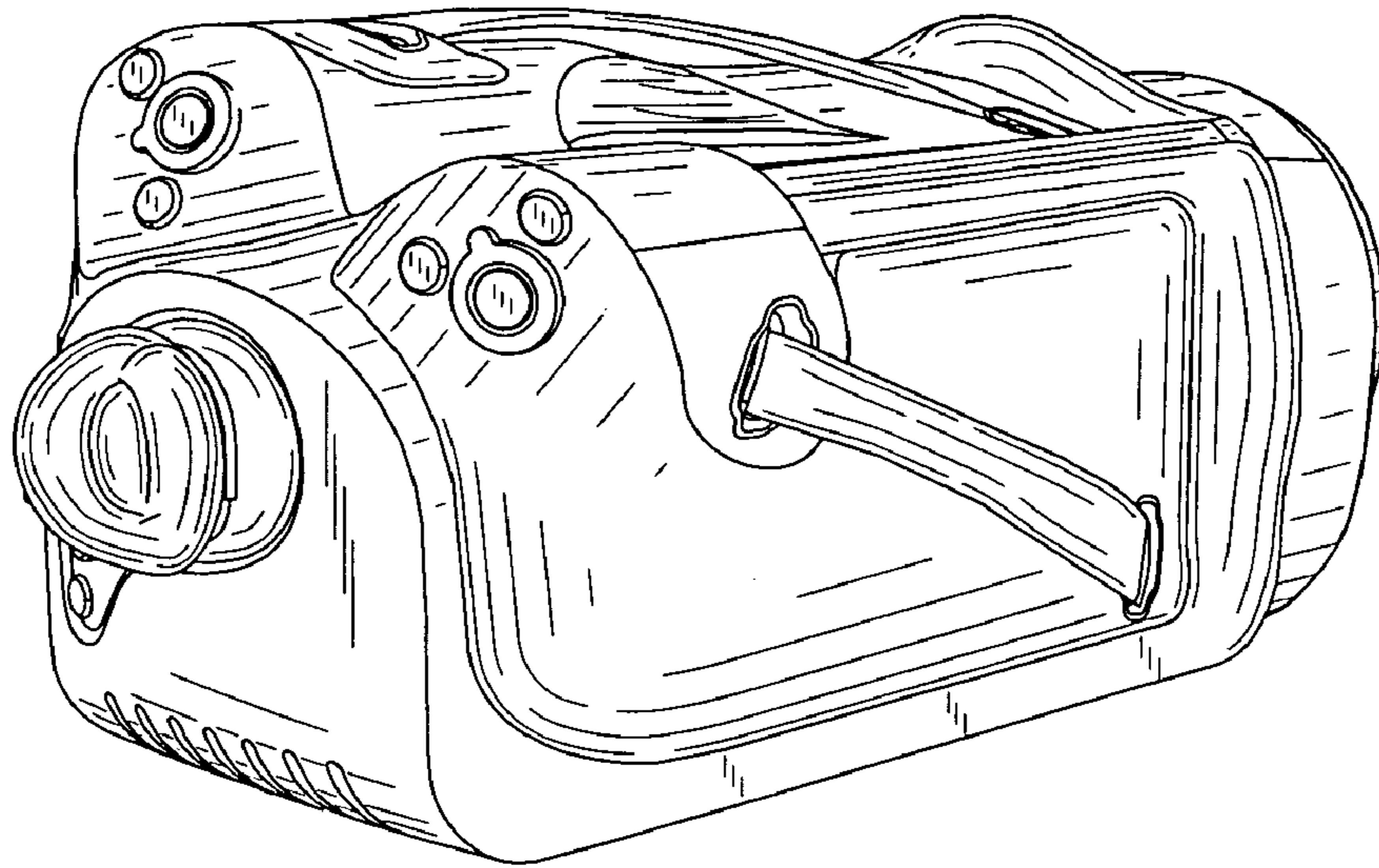


Fig. 7

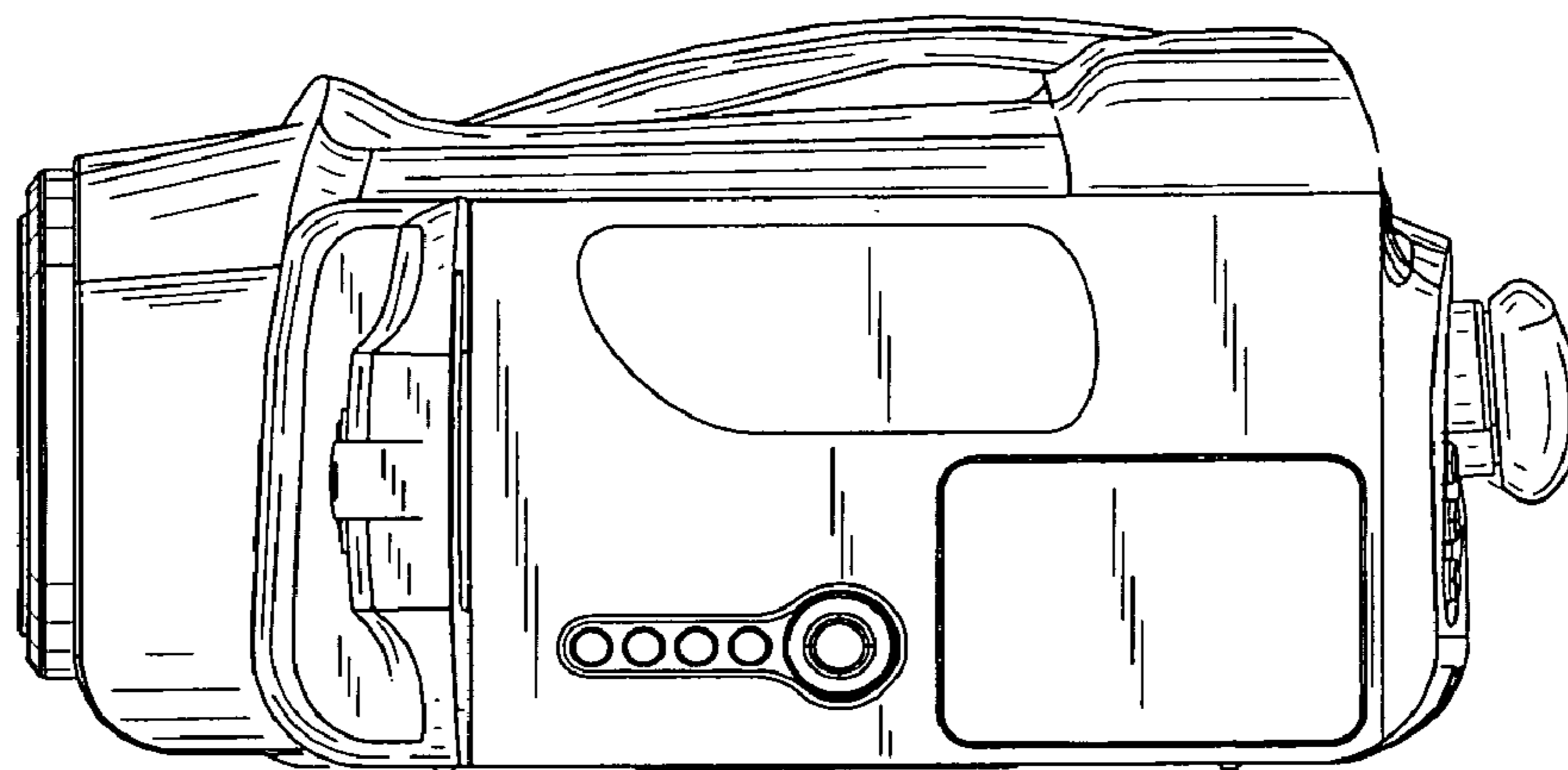


Fig. 8

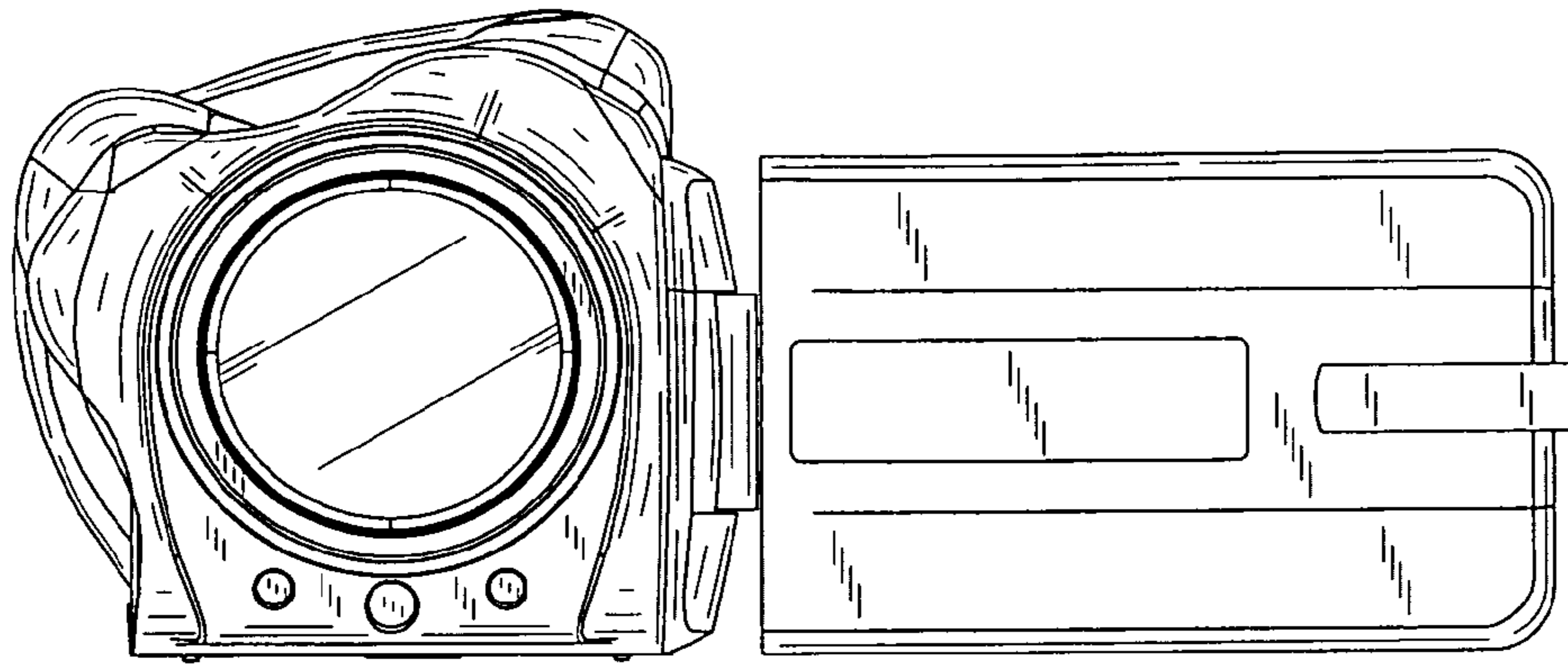


Fig. 9

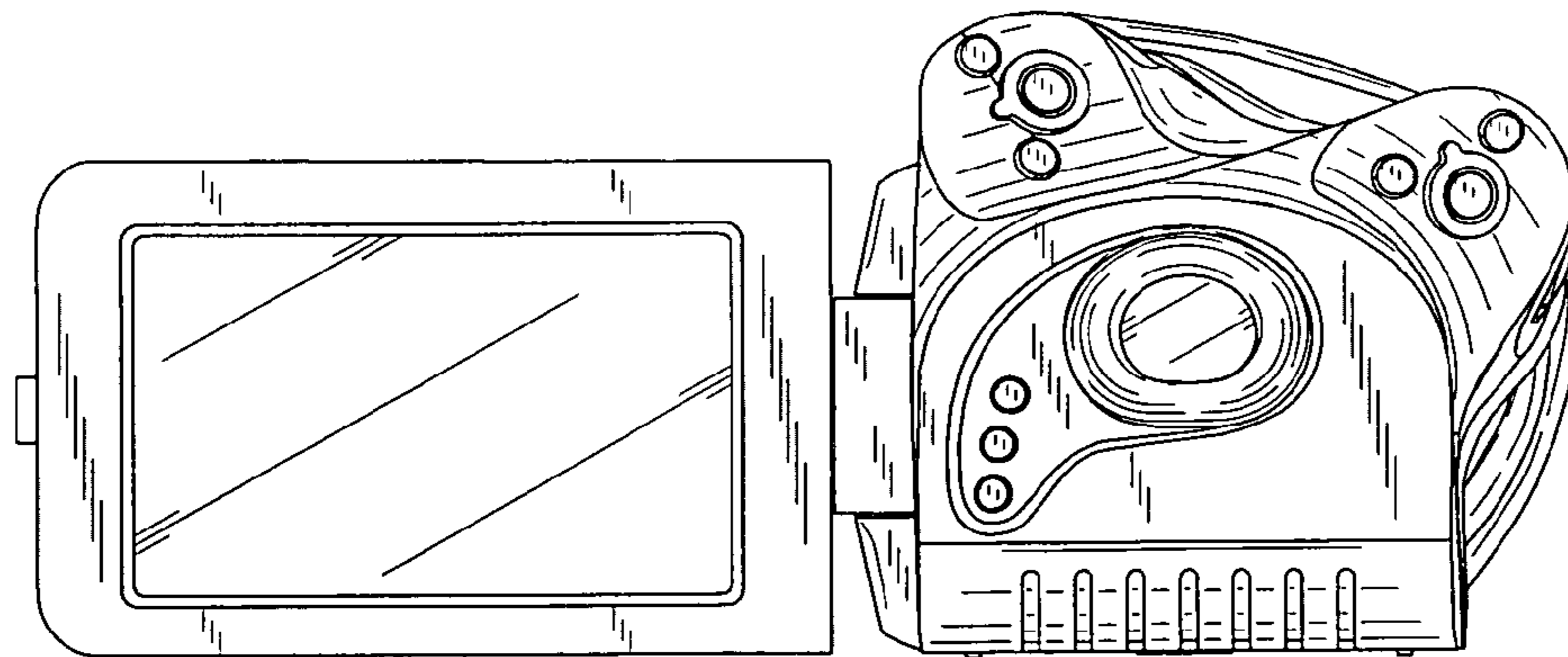


Fig. 10

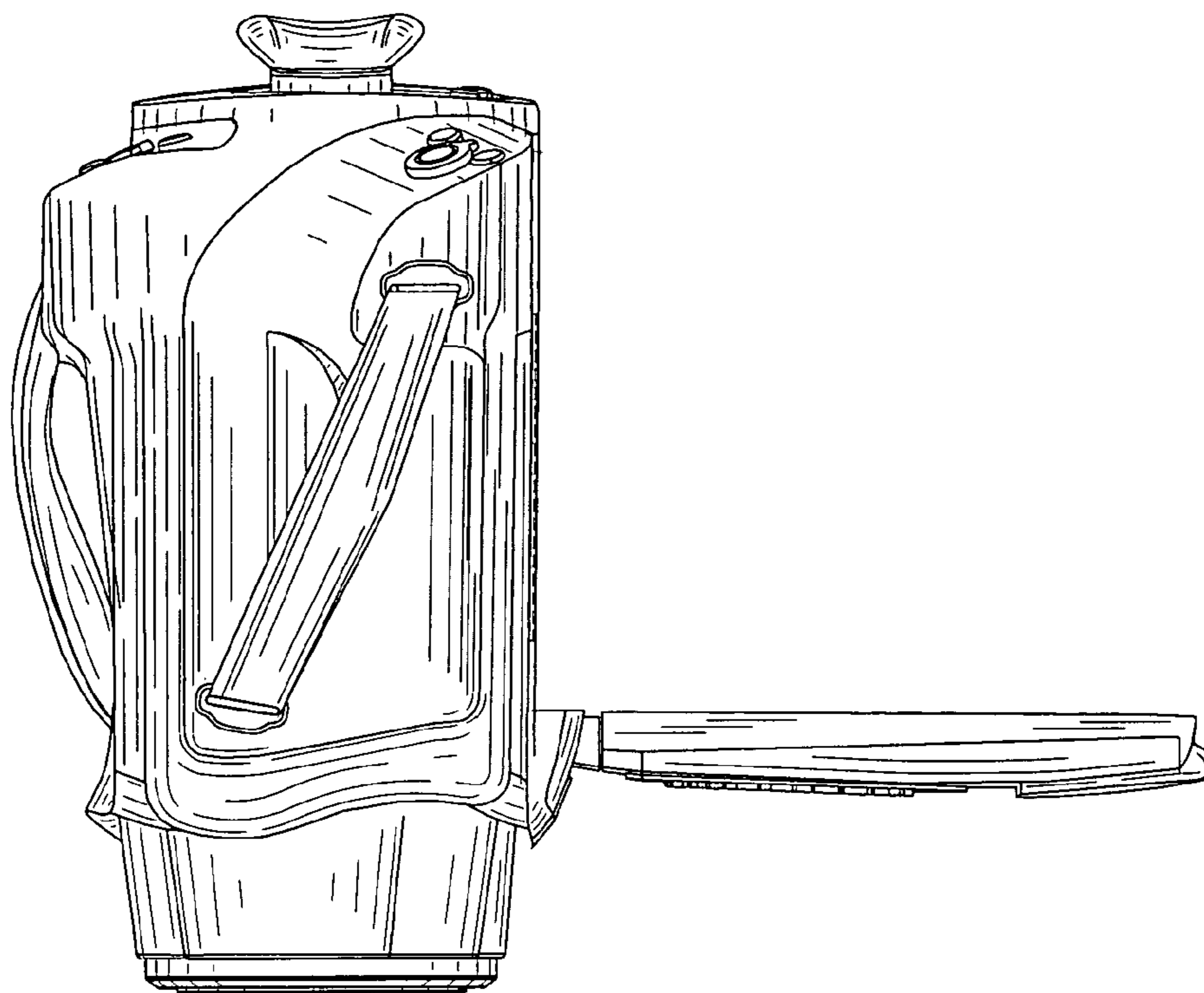


Fig. 11

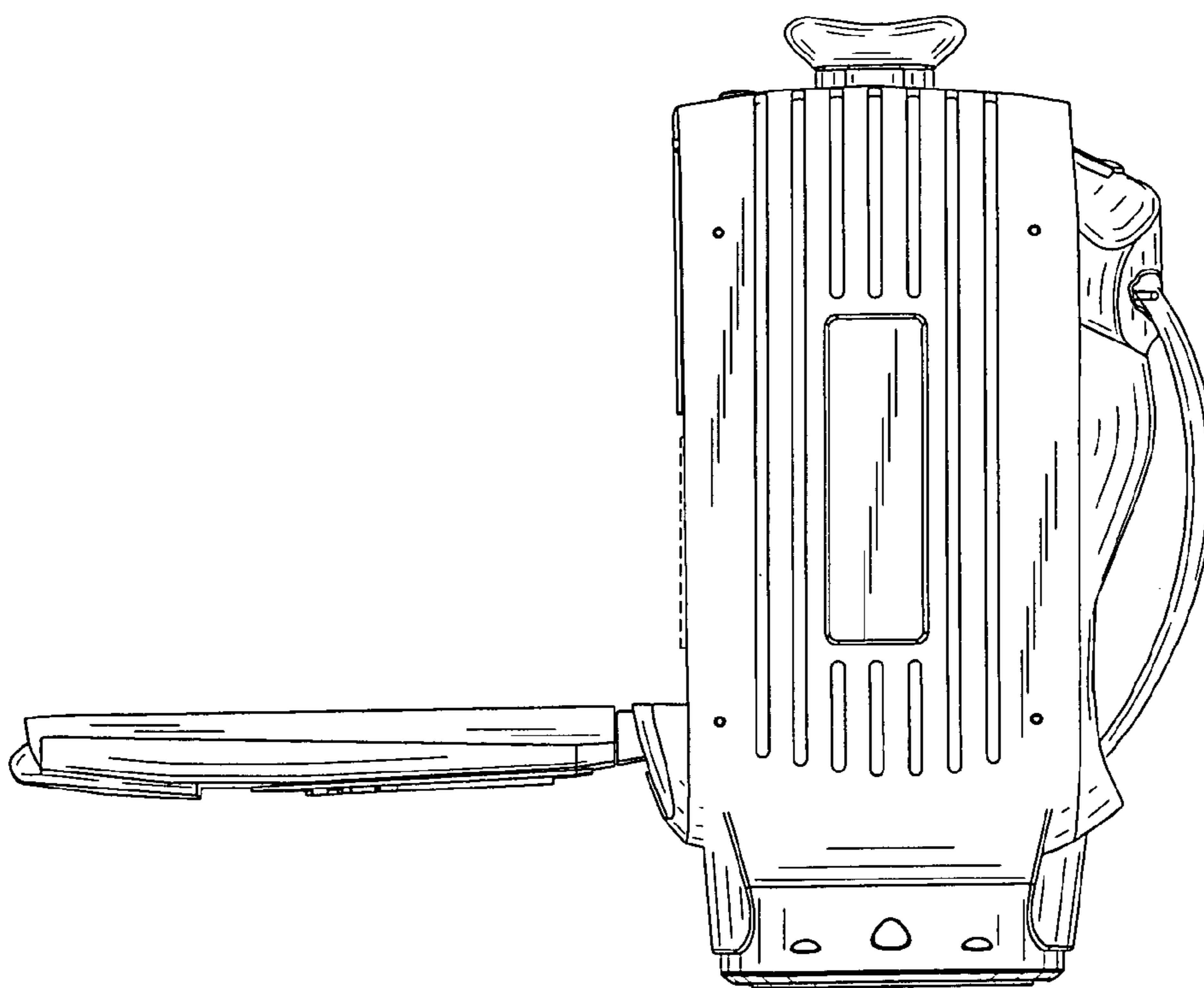


Fig. 12